

L Number	Hits	Search Text	DB	Time stamp
5	0	(gull adj wing) and (@ad<20001230) and (power adj (plane and bar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 14:19
6	0	(gull adj wing) and (@ad<20001230) and (power adj (plane and bar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:34
7	1	(@ad<20001230) and (power adj (plane and bar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 13:44
10	571	((257/\$.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor) and (socket with (board or substrate or pwb or pcb))) and (@ad<20001230)) and (bus or power)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 14:01
11	347	((257/\$.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor) and (socket with (board or substrate or pwb or pcb))) and (@ad<20001230)) and (bus or power) ) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 14:02
12	0	(gull adj wing) and (@ad<20001230) and (power adj (plane and pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 14:19
13	2	(gull adj wing) and (@ad<20001230) and (power adj pad) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 14:24
14	418	(gull adj wing) and (@ad<20001230) and power and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 15:08
15	54	(gull adj wing) and (@ad<20001230) and (power with (bus and lead or pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:40
16	107	"L54" and (electrical or electrically)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 15:09
17	52	((gull adj wing) and (@ad<20001230) and (power with (bus and lead or pad))) and (electrical or electrically)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 15:58
18	23	((gull adj wing) and (@ad<20001230) and (power with (bus and lead or pad))) and (electrical or electrically) and (ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:25
19	1706	current near power and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:25

20	1706	(current near power) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/09/06 16:28
21	1	("0504385").PN.	USPAT	2004/09/06 16:33
22	19	socket and (package or chip or die or (integrated adj circuit) or semiconductor) and (pin or pins) and ((bus or bar) with (bump or balls))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 17:21
23	12	(socket and (package or chip or die or (integrated adj circuit) or semiconductor) and (pin or pins) and ((bus or bar) with (bump or balls))) and (@ad<20001230)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:38
24	2420	socket and (package or chip or die or (integrated adj circuit) or semiconductor) and (pin or pins) and (bump or balls)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:39
25	1523	(socket and (package or chip or die or (integrated adj circuit) or semiconductor) and (pin or pins) and (bump or balls)) and (@ad<20001230)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:39
26	730	((socket and (package or chip or die or (integrated adj circuit) or semiconductor) and (pin or pins) and (bump or balls)) and (@ad<20001230) ) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 16:40
27	538	((socket and (package or chip or die or (integrated adj circuit) or semiconductor) and (pin or pins) and (bump or balls)) and (@ad<20001230) ) and power) and (board or pcb or pwb or (printed near board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 17:22
28	5	5610801.URPN.	USPAT	2004/09/06 17:10
29	6	("3829741"   "4439815"   "4683550"   "4997377"   "5268820"   "5384692").PN.	USPAT	2004/09/06 17:10
30	90	socket and (package or chip or die or (integrated adj circuit) or semiconductor) and (pin or pins) and (power with (bump or balls))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 17:21
31	226	socket and (package or chip or die or (integrated adj circuit) or semiconductor) and (pin or pins) and (power same (bump or balls))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 17:21
32	70	(socket and (package or chip or die or (integrated adj circuit) or semiconductor) and (pin or pins) and (power same (bump or balls))) and ((board or pcb or pwb or (printed near board)) with (hole or cavity or opening or recess or gap or space))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 17:23
33	30	((socket and (package or chip or die or (integrated adj circuit) or semiconductor) and (pin or pins) and (power same (bump or balls))) and ((board or pcb or pwb or (printed near board)) with (hole or cavity or opening or recess or gap or space))) and ((ball or balls or bump) with (hole or cavity or opening or recess or gap or space))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 17:23

-	2123	361/\$.ccls. and socket and (package or hcip or die or (integrated adj circuit) or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/06 16:33
-	121	361/788.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/03 19:53
-	88	(361/788.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor)) and (@ad<20001230)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/03 19:55
-	0	257/\$.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor) and socket and (board or substrate or pwb or pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/03 19:53
-	2480	257/\$.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor) and socket and (board or substrate or pwb or pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/03 19:54
-	1842	257/\$.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor) and (socket same (board or substrate or pwb or pcb))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/03 19:55
-	1517	257/\$.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor) and (socket with (board or substrate or pwb or pcb))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/03 19:55
-	1047	(257/\$.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor) and (socket with (board or substrate or pwb or pcb))) and (@ad<20001230)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/03 19:55
-	539	((257/\$.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor) and (socket with (board or substrate or pwb or pcb))) and (@ad<20001230)) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/03 19:56
-	571	((257/\$.ccls. and (package or chip or die or (integrated adj circuit) or semiconductor) and (socket with (board or substrate or pwb or pcb))) and (@ad<20001230)) and (bus or power)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/06 14:01